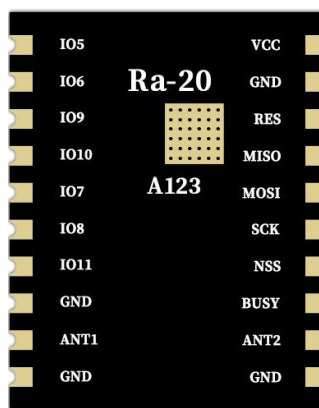


Ra-20 Specification



Product Series: LoRa Series

Product Model: Ra-20

Version: V1.0.3

Copyright: ©2026

Document Language: English

Release Date: 2026-09-18

Confidentiality Level: Public Document

Manufacturer: Shenzhen Ai-Thinker Technology Co., Ltd.

Keywords: LoRa, Semtech LR2021, Sub-GHz, 2.4GHz, RF Module, LR-FHSS, IoT

Document Revision History

Version	Date	Created / Revised Content	Prepared by	Approved by
V1.0.0	2026-05-07	First edition	Qiao Rongxin	Guan Ning
V1.0.1	2026-06-25	1. Modified RF interface description; 2. Updated antenna description	Qiao Rongxin	Guan Ning
V1.0.2	2026-07-02	Modified communication protocols supported by the module	Qiao Rongxin	Guan Ning
V1.0.3	2026-09-18	1. Updated module renderings; 2. Added frequency and transmit-power regulatory limits	Qiao Rongxin	Guan Ning

Contents

1 Product Overview	5
1.1 Features	6
1.2 Application Scenarios	7
2 Key Specifications	8
3 Electrical Characteristics	9
3.1 Recommended Operating Conditions	9
3.2 I/O DC Electrical Characteristics	9
3.3 Electrostatic Discharge	9
3.4 LoRa RF Performance	10
3.5 Power Consumption	12
4 Mechanical Specifications	13
4.1 Module Dimensions	13
4.2 External Antenna Connector Dimensions	14
5 Pin Definition	15
6 Schematic	17
7 Design Guide	18
7.1 Application Reference Circuit	18
7.2 Recommended PCB Footprint Dimensions	19
7.3 Power Supply	20
7.4 GPIO	21
8 Storage Conditions	22
9 Reflow Soldering Profile	22
10 Packaging Information	23
11 Contact Us	23
Disclaimer	24

List of Figures

Figure 1	Main Chip Architecture Diagram	5
Figure 2	ESD Protection Diagram	9
Figure 3	Module Dimensions (Unit: mm)	13
Figure 4	External Antenna Connector Dimensions (Unit: mm)	14
Figure 5	Pin Diagram	15
Figure 6	Schematic	17
Figure 7	Application Reference Circuit	18
Figure 8	Recommended PCB Footprint Dimensions (Unit: mm)	19
Figure 9	DC-DC Buck Circuit	20
Figure 10	Level-Shifting Circuit	21
Figure 11	Reflow Soldering Profile	22
Figure 12	Tape and Reel Packaging Diagram	23

List of Tables

Table 1	Key Specifications	8
Table 2	Recommended Operating Conditions	9
Table 3	I/O DC Electrical Characteristics	9
Table 4	LoRa RF Performance	10
Table 5	RF Regulatory Limits by Country / Region	11
Table 6	Instantaneous Power Consumption	12
Table 7	Pin Function Definition	15

1 Product Overview

The Ra-20 is an ultra-high-performance RF front-end module based on Semtech's fourth-generation LoRa Plus™ LR2021 RF chip. It is designed for IoT applications, long-range wireless communications, and wireless sensor networks for Industry 4.0 applications. Its key advantage lies in an ultra-compact package and extreme RF performance. By optimizing the collaborative design of power amplifier, low-noise amplifier, filter, and external matching network, it achieves high power, low loss, low spurious emissions, and strong interference immunity, while complying with major global regulatory and certification requirements.

The Ra-20 module supports Sub-GHz and 2.4GHz ISM bands. It features three key capabilities: ultra-long-range transmission, high-speed data throughput, and global single-SKU adaptability.

Figure 1 shows the LR2021 main chip architecture.

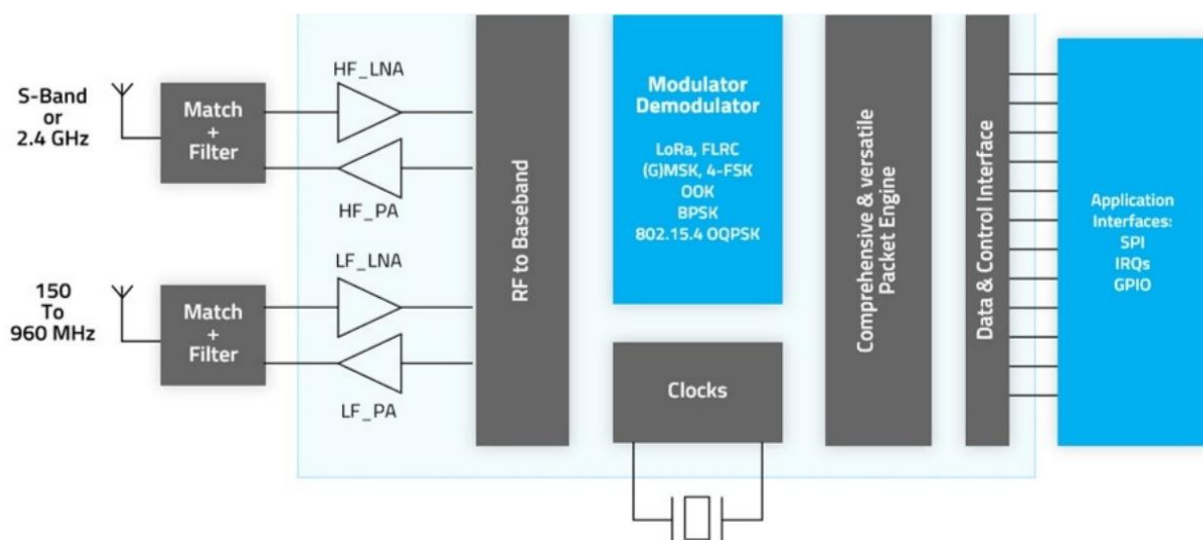


Figure 1 Main Chip Architecture Diagram

1.1 Features

RF Performance

- Transmit power: measured maximum transmit power of 21.5dBm@Sub-GHz, 12dBm@2.4GHz
- Power flatness: $\leq \pm 0.5\text{dBm}$. Stable full-band and full-power transmission and the power level is software-adjustable in multiple steps
- Receiver sensitivity:
 - Sub-GHz: up to -147dBm@BWLORA = 31kHz / SF12 / CR4/5 (refer to chip datasheet)
 - 2.4GHz: up to -137.5dBm@BWLORA = 200kHz / SF12 / CR4/5 (refer to chip datasheet)
- Frequency offset tolerance: $\pm 33\%$ BW, far exceeding the previous generation's $\pm 25\%$ BW. High-precision frequency stability can be achieved without a TCXO
- Harmonic suppression: 490MHz@22dBm 2nd and 3rd harmonics $\leq -40\text{dBm}$, 2450MHz@12dBm 2nd and 3rd harmonics $\leq -40\text{dBm}$, with sufficient margin to pass CE, FCC and other regulations
- The module requires an external MCU to adjust the transmit power and operating frequency, which must be configured by the user in strict compliance with the regulations of the relevant country or region.

Operating Frequency Bands

- Sub-GHz: 470 – 510MHz by default for China (433MHz can be customized)
- 2.4GHz: 2400 – 2500MHz by default for China

Power Consumption

- Sleep current: $\leq 2\mu\text{A}$ (average value: 1.65)
- Receive current: $\leq 6\text{mA}$
- Transmit current: Sub-GHz@22dBm 125.8mA; 2.4GHz@12dBm 27mA

Communication and Protocols

- Data rate: up to 2.6Mbps in FLRC mode and 125kbps in LoRa mode
- Supports fourth-generation LoRa IP technology and LR-FHSS
- Protocol compatibility (Only the physical layer is supported; the protocol layer needs to be developed by the customer):

- LoRa / LoRaWAN® at Sub-GHz and 2.4GHz
- Amazon Sidewalk
- Bluetooth® LE 5.0 PHY compatible
- IEEE® 802.15.4™ Thread® and Zigbee™ O-QPSK
- Sigfox BPSK
- Wi-SUN FSK
- Wireless M-BUS (device and collector)
- Z-Wave® and Z-Wave LR
- 2-FSK and 4-FSK based protocols

Physical Characteristics

- Package: SMD-20
- Module dimensions (L × W × H): 20.00 × 16.00 × 3.20mm
- Antenna type: IPEX Gen 1 connector / castellated antenna
- Operating temperature: -40 – 85°C
- Storage conditions: -40 – 125°C, < 90% RH

Electrical Characteristics

- Supply voltage: 1.8 – 3.7V (typical value 3.3V)
- Supply current: > 200mA
- Communication interface: standard SPI interface
- Available I/Os: 7 GPIOs by default
- Protection: built-in ESD protection circuit

Note: For features not marked, please refer to the official Semtech LR2021 chip datasheet.

1.2 Application Scenarios

- Smart Industry
- Energy Monitoring
- Outdoor IoT
- Consumer Electronics

2 Key Specifications

Table 1 summarizes the key electrical and physical parameters of the Ra-20 module.

Table 1 Key Specifications

Model	Ra-20
Package	SMD-20
Dimensions	20.00 × 16.00 × 3.20mm
Antenna Type	IPEX Gen 1 connector / castellated antenna
Frequency Range	470 – 510MHz; 2400 – 2500MHz
Operating Temperature	-40 – 85°C
Storage Conditions	-40 – 125°C, <90% RH
Power Supply Range	Supply voltage: 1.8 – 3.7V, typical 3.3V; supply current > 200mA
Communication Interface	SPI
Available I/Os	7 by default

3 Electrical Characteristics

3.1 Recommended Operating Conditions

Table 2 lists the recommended operating electrical parameters of the Ra-20 module. Operating outside these ranges may cause device damage.

Table 2 Recommended Operating Conditions

Symbol	Parameter	Min	Typ	Max	Unit
VCC	Supply Voltage	1.8	3.3	3.7	V
I	Supply Current	200	-	-	mA

3.2 I/O DC Electrical Characteristics

Table 3 lists the I/O DC characteristics of the Ra-20 module. These parameters are mainly used for external interface level matching and GPIO circuit design.

Table 3 I/O DC Electrical Characteristics

Symbol	Parameter	Min	Typ	Max	Unit
VIH	High-level Input Voltage	$0.7 \times VCC$	-	$VCC + 0.3$	V
VIL	Low-level Input Voltage	-0.3	-	$0.3 \times VCC$	V
VOH	High-level Output Voltage	-	$0.9 \times VCC$	-	V
VOL	Low-level Output Voltage	-	-	$0.1 \times VCC$	V
ZPUD	Pull-up/Pull-down Resistors	-	40	100	k Ω

3.3 Electrostatic Discharge

Figure 2 shows the ESD protection diagram. Ra-20 is an ESD-sensitive device and requires special precautions during handling.



Figure 2 ESD Protection Diagram

3.4 LoRa RF Performance

Table 4 lists the LoRa RF performance parameters of the Ra-20 module. RF performance parameters are measured under typical test conditions. Actual performance may be affected by the antenna, power supply, PCB layout, test environment, and other factors.

Table 4 LoRa RF Performance

Description	Typ			Unit
Frequency Range	2400 – 2500			MHz
2.4GHz Output Power (Software Setting 12)				
Mode	Min	Typ	Max	Unit
2400MHz	-	-	12	dBm
2450MHz	-	-	12	dBm
2500MHz	-	-	12	dBm
2.4GHz Receiver Sensitivity (BW = 400kHz, SF7, CR4/5)				
Mode	Min	Typ	Max	Unit
2400MHz	-	-	-120	dBm
2450MHz	-	-	-120	dBm
2500MHz	-	-	-120	dBm
2.4GHz Harmonic Suppression RBW/VBW (1MHz / 3MHz)				
Mode	Min	Typ	Max	Unit
2450MHz@12dBm@2nd Harmonic	-	-48	-	dBm
2450MHz@12dBm@3rd Harmonic	-	-48	-	dBm
Description	Typ			Unit
Frequency Range	470 – 510			MHz
Sub-GHz Output Power (Software Setting 22)				
Mode	Min	Typ	Max	Unit
470MHz	-	-	21.5	dBm

490MHz	-	-	21.5	dBm
510MHz	-	-	21.5	dBm
Sub-GHz Receiver Sensitivity (BW = 400kHz, SF7, CR4/5)				
Mode	Min	Typ	Max	Unit
470MHz	-	-	-122.5	dBm
490MHz	-	-	-122.5	dBm
510MHz	-	-	-122.5	dBm
Sub-GHz Harmonic Suppression RBW/VBW (1MHz / 3MHz)				
Mode	Min	Typ	Max	Unit
490MHz@22dBm@2nd Harmonic	-	-45.5	-	dBm
490MHz@22dBm@3rd Harmonic	-	-45.5	-	dBm

Table 5 lists the regulatory requirements for common countries and regions. The module requires an external MCU to adjust the transmit power and operating frequency, which must be configured by the user in strict compliance with the regulations of the relevant country or region. The configurable Sub-GHz transmit power range is -10 to +22dBm, while the configurable 2.4GHz transmit power range is -17 to +12dBm.

Table 5 RF Regulatory Limits by Country / Region

Country / Region	Regulation	Operating Band	Power Limit
Mainland China	Document No. 52 (2019)	470 – 510MHz	ERP ≤ 17dBm
Mainland China	Document No. 129 (2021)	2400 – 2483.5MHz	EIRP ≤ 20dBm
European Union	CE	433.05 – 434.79MHz	ERP ≤ 10dBm
European Union	CE	863 – 870MHz	ERP ≤ 14dBm
European Union	CE	2400 – 2483.5MHz	EIRP ≤ 20dBm
North America	FCC	902 – 928MHz	EIRP ≤ 30dBm
North America	FCC	2400 – 2483.5MHz	EIRP ≤ 30dBm

Notes:

- $ERP\ (dBm) = Pt\ (dBm) - \text{Cable Loss}\ (dB) + \text{Antenna Gain}\ (dBd)$

- $EIRP\ (dBm) = Pt\ (dBm) - Cable\ Loss\ (dB) + Antenna\ Gain\ (dBi)$

According to the sample code on Ai-Thinker's official website, the procedures for configuring transmit power and operating frequency are as follows:

- * @param [in] radio Pointer to radio data structure
- * @param [in] output_pwr_in_dbm Output power - in dBm
- * @param [in] rf_freq_in_hz RF frequency - in Hertz

```
static inline ral_status_t ral_set_tx_cfg( const ral_t* radio, const int8_t output_pwr_in_dbm,
const uint32_t rf_freq_in_hz )
```

For questions regarding the above configuration, please contact Ai-Thinker.

3.5 Power Consumption

Table 6 lists the power consumption data of the Ra-20 module in different modes. The following power consumption data are measured under a 3.3V power supply and 25°C ambient temperature.

- The P_{OUT} power for all transmit modes is measured at the antenna interface.
- All transmission data are measured at 100% duty cycle in continuous transmit mode.

Table 6 Instantaneous Power Consumption

Mode	Min	Avg	Max	Unit
2.4GHz@TX (12dBm)	-	27	-	mA
Sub-GHz@TX (22dBm)	-	125.8	-	mA
2.4GHz@RX	-	6	-	mA
Sub-GHz@RX	-	5.87	-	mA
Standby Current	-	1.15	-	mA
Sleep Current	-	1.65	-	μA

4 Mechanical Specifications

4.1 Module Dimensions

Figure 3 shows the outline dimensions of the Ra-20 module. The outline dimensions ($L \times W \times H$) are $20.00 \times 16.00 \times 3.20\text{mm}$. The dimensional tolerance is $\pm 0.20\text{mm}$.

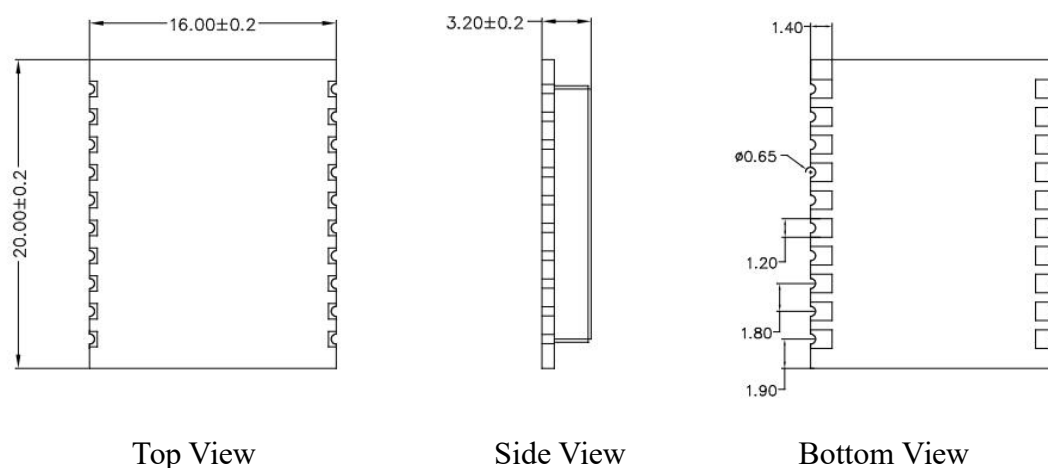


Figure 3 Module Dimensions (Unit: mm)

4.2 External Antenna Connector Dimensions

Figure 4 shows the engineering drawing of the IPEX antenna connector used with Ra-20. This connector is used to connect an external 50Ω RF antenna.

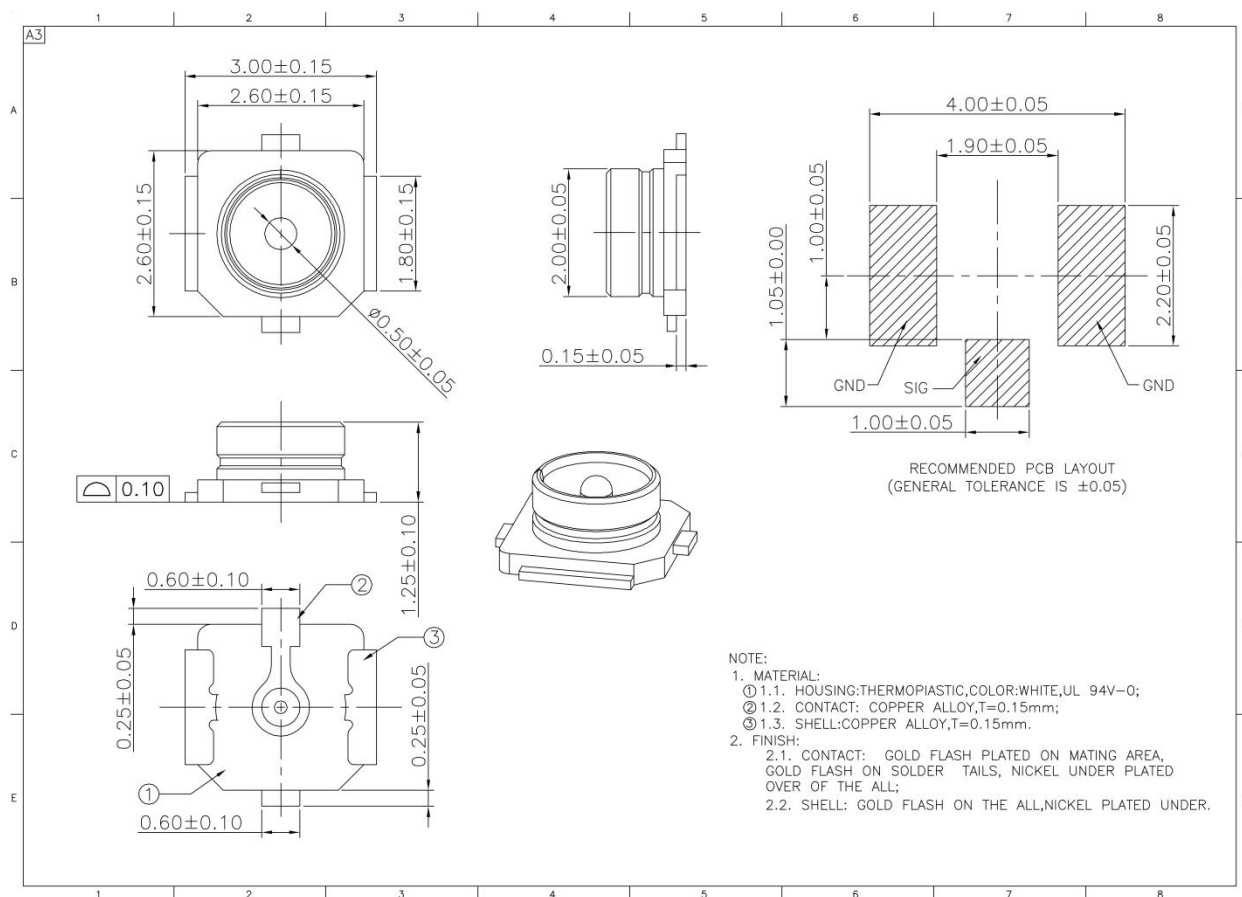


Figure 4 External Antenna Connector Dimensions (Unit: mm)

5 Pin Definition

Figure 5 shows the top and bottom views of the Ra-20 module's pin layout, with a total of 20 pins exposed.

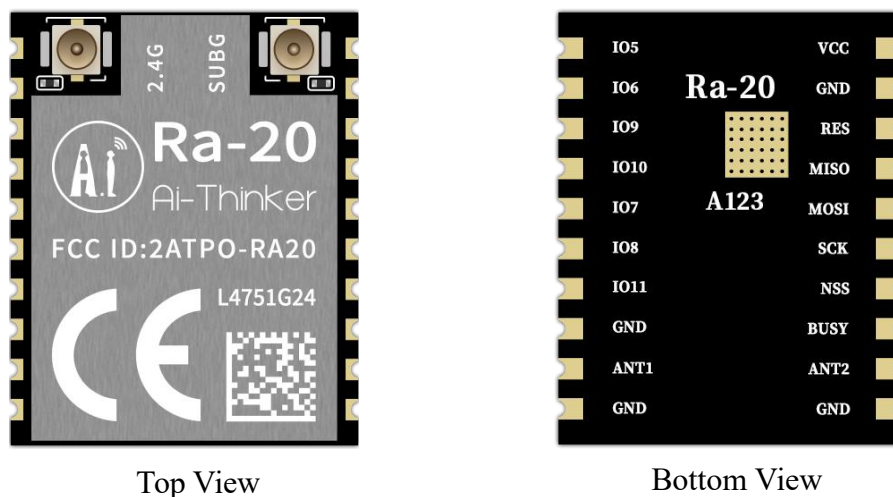


Figure 5 Pin Diagram

Table 7 defines the pin functions of the Ra-20 module, including pin number, pin name, and function description.

Table 7 Pin Function Definition

No.	Name	Function
1	GND	Module ground
2	ANT1	2.4GHz antenna interface, external 50Ω antenna
3	GND	Module ground
4	IO11	Multi-purpose digital interface; refer to the chip datasheet for details
5	IO8	Multi-purpose digital interface; refer to the chip datasheet for details
6	IO7	Multi-purpose digital interface; refer to the chip datasheet for details
7	IO10	Multi-purpose digital interface; refer to the chip datasheet for details
8	IO9	Multi-purpose digital interface; refer to the chip datasheet for details
9	IO6	Multi-purpose digital interface; refer to the chip datasheet for details
10	IO5	Multi-purpose digital interface; refer to the chip datasheet for details
11	VCC	Connect to the positive terminal of the power supply

12	GND	Connect to the negative terminal of the power supply
13	RES	Reset trigger input; refer to the chip datasheet for details
14	MISO	SPI data output
15	MOSI	SPI data input
16	SCK	SPI clock input
17	NSS	SPI chip select input
18	BUSY	Used for status indication; refer to the chip datasheet for details
19	ANT2	Sub-GHz antenna interface, external 50Ω antenna
20	GND	Module ground

6 Schematic

Figure 6 shows the schematic of the Ra-20 module, integrating RF antennas, power supply, clock, and reserved peripheral interfaces.

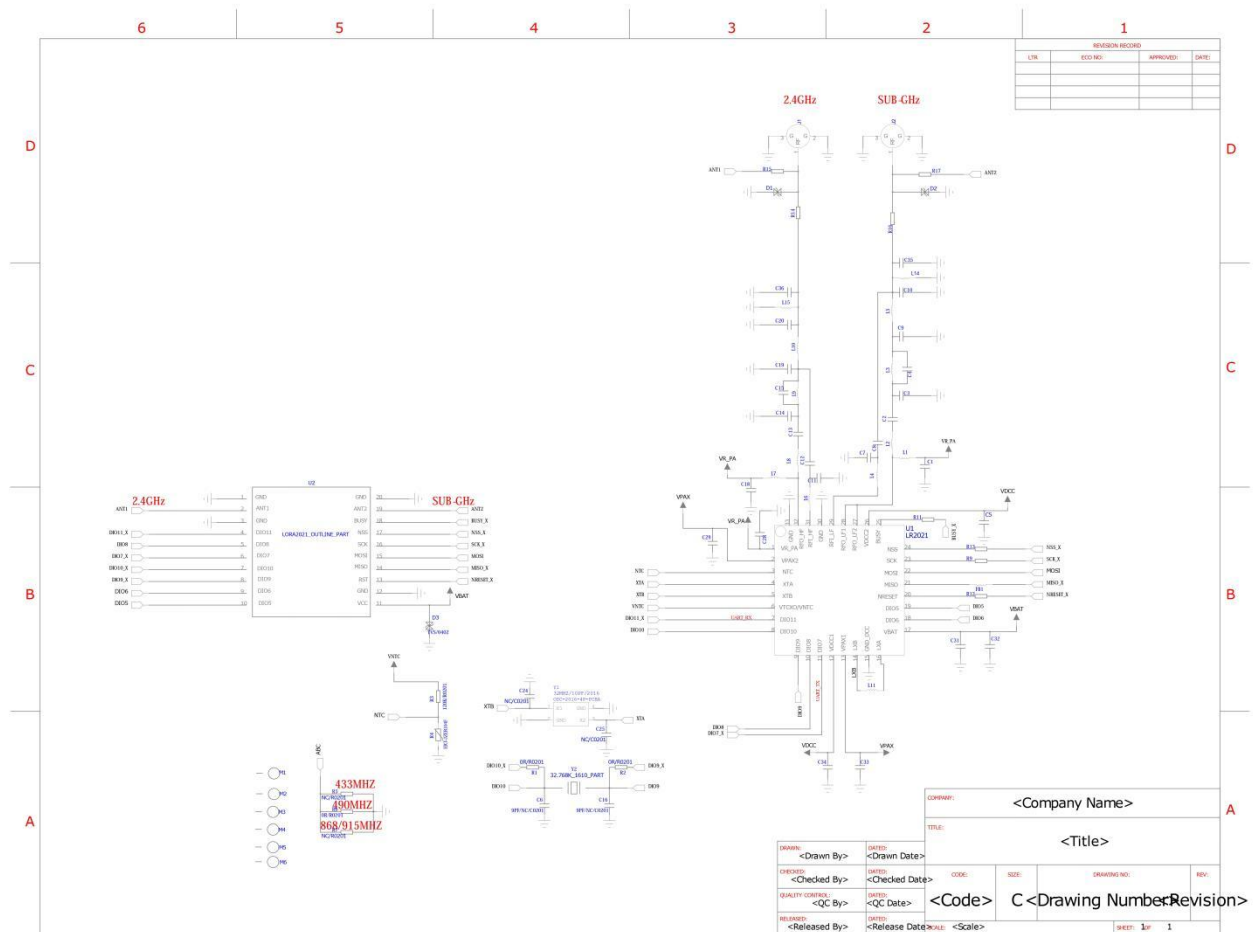


Figure 6 Schematic

7 Design Guide

7.1 Application Reference Circuit

Figure 7 shows the hardware application reference circuit of the Ra-20 module. The numbers in parentheses correspond to the module pin numbers.

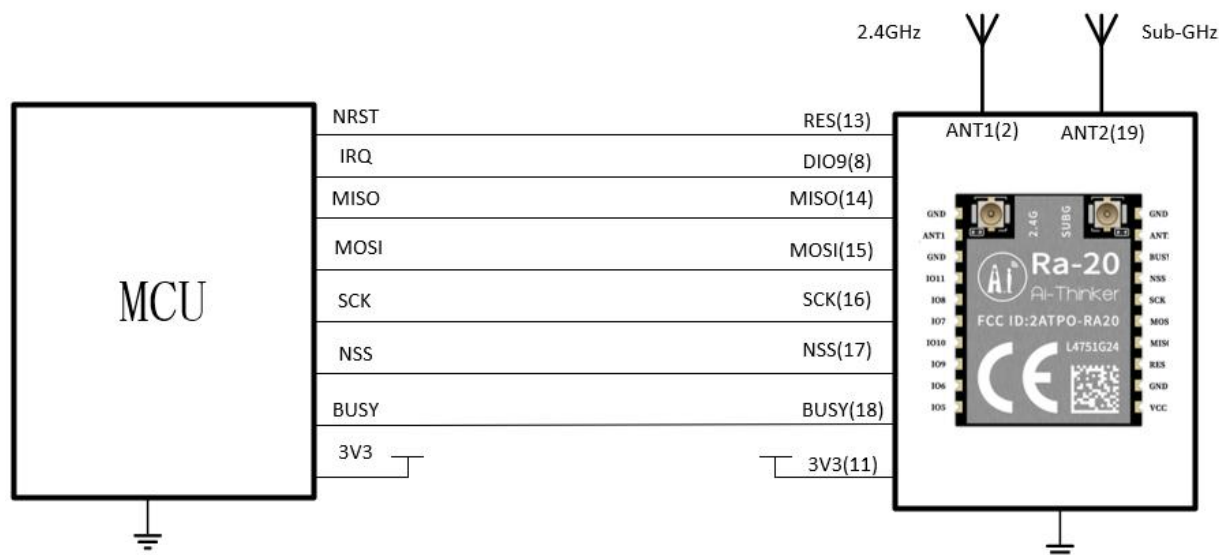


Figure 7 Application Reference Circuit

Notes on the Application Reference Circuit:

- VCC supply voltage: 1.8 – 3.7V. The external power supply output current is recommended to be above 200mA.
- RF specifications: LoRa ISM 470 – 510MHz; 2.4GHz wireless band.
- Communication interface: standard SPI communication (NSS/SCK/MOSI/MISO), compatible with host MCU SPI peripherals.
- Ra-20 is a LoRa Sub-GHz + 2.4GHz dual-mode wireless module. The Sub-GHz and 2.4GHz antennas operate independently for transmission and reception and must not be shared.

7.2 Recommended PCB Footprint Dimensions

Figure 8 shows the recommended PCB footprint dimensions of the Ra-20 module. The pad dimensions (L × W) are $2.60 \times 1.20\text{mm}$. The center-to-center spacing between adjacent pads is 1.80mm .

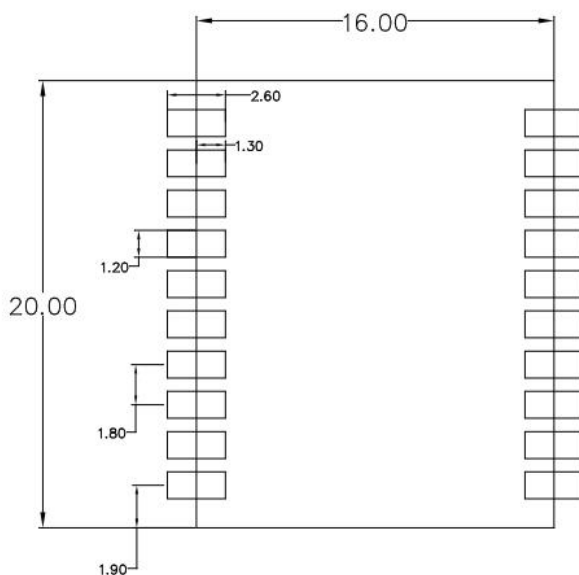


Figure 8 Recommended PCB Footprint Dimensions (Unit: mm)

7.4 GPIO

Figure 10 shows a 3.3V and 5V bidirectional UART level-shifting circuit, which supports bidirectional serial communication across different voltage levels.

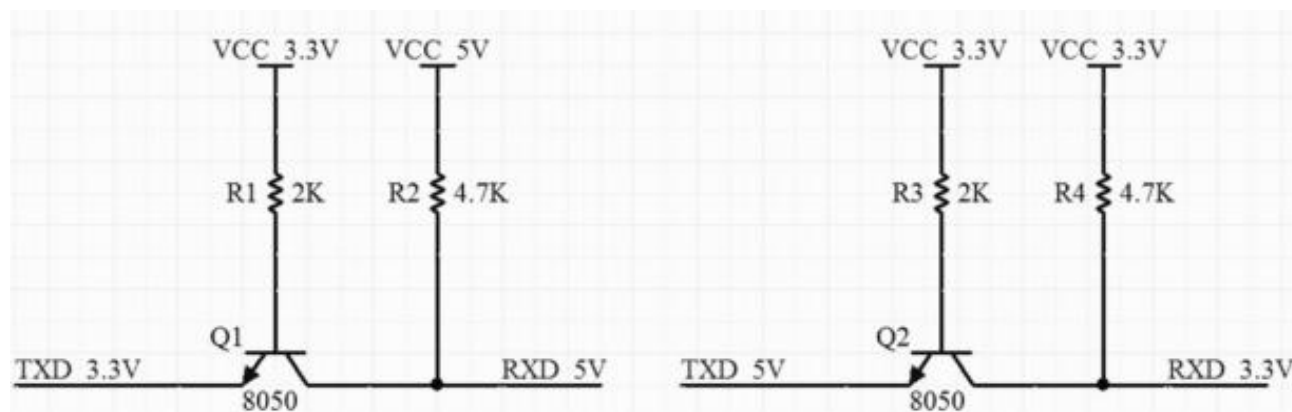


Figure 10 Level-Shifting Circuit

Notes on the Level-Shifting Circuit:

- Some I/O pins are exposed on the module. To use these I/O pins, it is recommended to connect a 10-100Ω resistor in series with each I/O pin. This helps suppress overshoot, stabilize signal levels, and benefits both EMI and ESD protection.
- The pull-up or pull-down configuration for special I/O pins must refer to the instructions in the specification, as it affects the module boot configuration.
- The module I/O pins level is 3.3V. If the host controller I/O voltage level does not match the module, a level-shifting circuit should be added.
- If an I/O pin is directly connected to a peripheral interface or pin headers, it is recommended to reserve space for an ESD protection device near the connector on the I/O trace.

8 Storage Conditions

Products sealed in moisture barrier bags should be stored in a non-condensing atmosphere at $< 40^{\circ}\text{C}$ and $< 90\% \text{ RH}$.

The moisture sensitivity level (MSL) of the module is level 3.

The module must be used within 168 hours after vacuum bag removal under conditions of $25 \pm 5^{\circ}\text{C}$ and 60% RH. Otherwise, the module requires baking before being returned to production.

9 Reflow Soldering Profile

Figure 11 shows the module reflow soldering process profile. The process is divided into four stages: ramp-up zone, preheat/soak zone, reflow soldering zone and cooling zone.

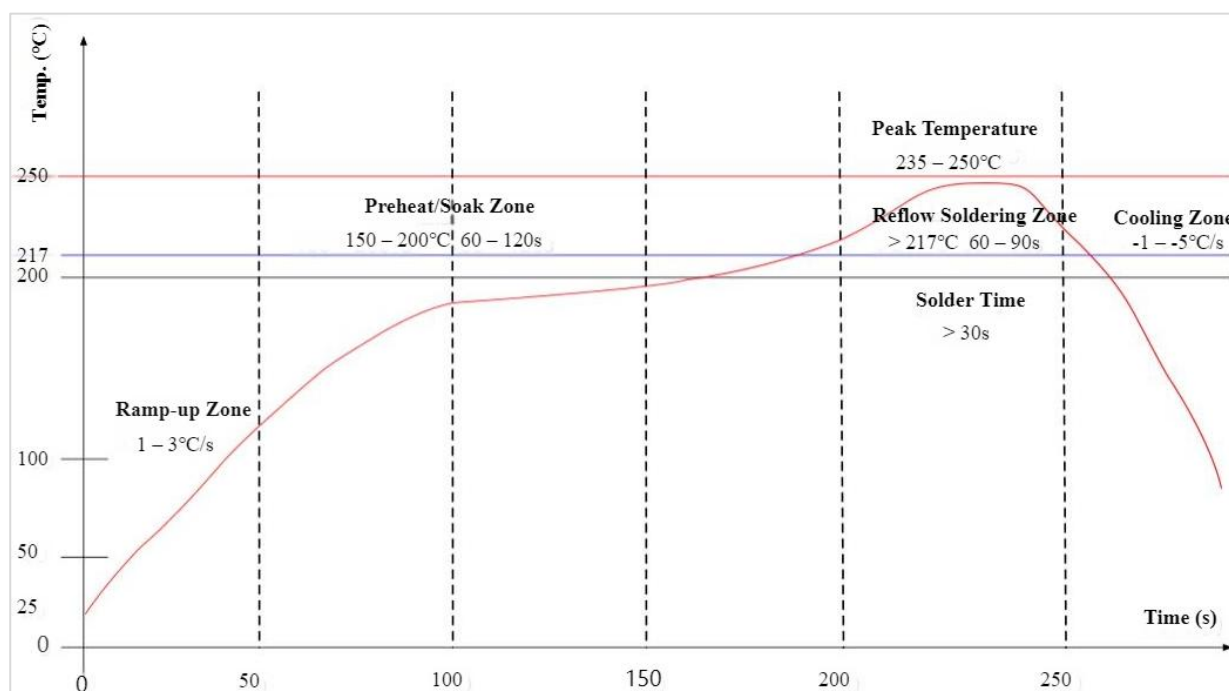


Figure 11 Reflow Soldering Profile

Reflow Soldering Profile Description:

- Ramp-up zone – Temperature: $25 - 150^{\circ}\text{C}$, Time: 60 – 90s, Ramp rate: $1 - 3^{\circ}\text{C/s}$
- Preheat/soak zone – Temperature: $150 - 200^{\circ}\text{C}$, Time: 60 – 120s
- Reflow soldering zone – Temperature: $> 217^{\circ}\text{C}$, Time: 60 – 90s, Peak temperature: $235 - 250^{\circ}\text{C}$, Time: 30 – 70s
- Cooling zone – Temperature: peak temperature to 180°C , Cooling rate: $-1 - -5^{\circ}\text{C/s}$
- Solder – Sn-Ag-Cu lead-free solder alloy (SAC305)

10 Packaging Information

Figure 12 shows the packaging of the Ra-20 module. The module is packed in tape-and-reel, 800 pcs/reel.



Figure 12 Tape and Reel Packaging Diagram

11 Contact Us

[Official Website](#)

[Official Forum](#)

[Development DOCS](#)

[LinkedIn](#)

[Tmall Store](#)

[Taobao Store](#)

[Alibaba Store](#)

[Technical Support: support@aithinker.com](mailto:support@aithinker.com)

[Domestic Business Cooperation: sales@aithinker.com](mailto:sales@aithinker.com)

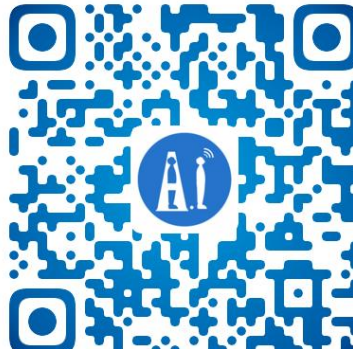
[Overseas Business Cooperation: overseas@aithinker.com](mailto:overseas@aithinker.com)

Company Address: Room 403–405, 408–410, Building C, Huafeng Smart Innovation Port, Gushu, Xixiang, Bao'an District, Shenzhen, Guangdong, China

Contact Hotline: 0755-29162996



WeChat Mini Program



WeChat Official Account

Disclaimer

The data contained in this specification are typical test values obtained by Ai-Thinker laboratory and are provided for reference only. Actual performance may vary depending on the application environment and shall be subject to actual verification. Ai-Thinker reserves the right to modify this document at any time. Please refer to the official documentation website for the latest version. To the maximum extent permitted by applicable laws and regulations, Ai-Thinker shall not be liable for any losses arising from the use of this specification. All trademarks mentioned herein are the property of their respective owners. No part of this specification may be reproduced or used for commercial promotion without prior written permission. This specification does not grant any license to any intellectual property rights.